



CUSTOM EPOXY RESINS FOR EVTOL

Resin Formulators, the custom formulation division of GracoRoberts, is the time-tested and trusted brand of EVTOL epoxy resins that can be uniquely customized, tested and certified on-demand.

Customers benefit from our world-class technical and service experts who are dedicated to understanding the unique regulatory and material performance requirements of the EVTOL market. Our extensive selection of tested and approved products for EVTOL include solutions for structural bonding, composite solutions, electrically conductive adhesives, thermal interface materials, and electronic materials.

Our innovative solutions serve many of the leading manufacturers in the EVTOL space, and have solved complex challenges in nearly every manufacturing industry for over 60 years.

COMMITMENT TO QUALITY AND SERVICE

GracoRoberts and Resin Formulators are fully qualified to design, manufacture, and distribute products to a variety of industries. We are independently certified to three rigorous international quality standards: ISO 9001:2015, AS9100 (Rev. D) and AS9120 (Rev. B).

EVTOL FEATURED PRODUCTS

| Application | Product | Capabilities |
|---------------------------------|---------------------|---|
| Edge Filling and Insert Bonding | RF 1149FR | A two-component low density syntactic with excellent flame retardant properties meeting FAR 25 requirements. This product is thixotropic and can be used on vertical surfaces without excessive run out from the application zone. Moderately reactive formula providing a work life of 40 mins, and will fully cure in 3-5 days at room temp. Product cure can be accelerated with heat after the product has set at room temperature. |
| | RF 1148FR | A high strength, syntactic potting compound formulated to meet UL 94 V0 flammability requirements. It features a rapid set time and non-slump handling characteristics. |
| Structural Bonding | RF 2070 | A two-component toughened paste adhesive, which combines high peel strength at room temperature with lap shear strength retention to 225°F (107°C). Glass beads are added for bond line control. |
| | RF 6100 | Medium viscosity, high temperature bonding adhesive with service conditions up to 350 °F. It is ideal for metal and composite structures. |
| | RF 6110 | A two-part volume dispensing structural adhesive system. Designed to cure at room temperature, it is also capable of elevated curing. |
| | RF 8907 | A two-part room temperature curing structural adhesive with excellent shear performance at elevated temperatures. Microbeads are included for bond line control. |
| Thermal Management | RF 2969 (Mod 7) | A thixotropic, high strength epoxy adhesive with good physical strength and high electrical conductivity. This material is designed where hot solder applications are impractical or on parts which cannot be subjected to heat. It is also effective as a shielding material. |
| | RF 5407 | Easy-to-use, alumina-filled, liquid epoxy resin with excellent electrical insulation properties, high thermal conductivity, and high service temperatures. When used with RF 24* the cured product will have low shrinkage, excellent thermal stability and conductivity, and be a strong and durable casting. |
| | *RF 24 Curing Agent | A cycloaliphatic amine curing agent used to cure various epoxy resins at elevated temperatures. The properties of RF 24 include light color, low viscosity, long pot life, and rapid cure. |